

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-2. (Cancelled)

3. (Currently Amended) A method for manufacturing an electronic module, comprising:

- taking a first sheet, which has a first and a second surface, and which first sheet includes an insulating-material layer between the first and the second surface, as well as a first conductive layer on the first surface,
- making at least one first recess in the first sheet that extends through the second surface and the insulating-material layer as far as the first conductive layer, which covers the first recess from the direction of the first surface,
- taking a first component having a contact surface with contact areas or contact protrusions,
- placing the first component in the first recess with its contact surface facing the first surface,
- attaching the first component to the first conductive layer by gluing with the aid of an electrically insulating adhesive,
- forming a first conductive pattern from the first conductive layer and forming [[a]] at least some first electrical contacts ~~contact~~ between the first component and the first conductive pattern ~~by making through~~ first feed-throughs, the first electrical contacts connecting which connect at least some of the contact areas or contact protrusions of the first component electrically to the first conductive pattern,

- making a second conductive layer on the second surface of the first sheet,
- making at least one second recess in the first sheet, which extends through the first surface and the insulating-material layer as far as the second conductive layer, which covers the second recess from the direction of the second surface,
- taking a second component having a contact surface with contact areas or contact protrusions,
- placing the second component in the second recess, with its contact surface towards the second surface, and attaching the second component to the second conductive layer by gluing with the aid of a second electrically insulating adhesive, and
- forming a second conductive pattern from the second conductive layer and forming [[a]] at least some second electrical ~~contacts~~ ~~contact~~ between the second component and the second conductive pattern by making through second feed-throughs, the second electrical contacts connecting ~~which connect~~ at least some of the contact areas or contact protrusions of the second component electrically to the second conductive pattern.

4. (Cancelled)

5. (Withdrawn) A method according to Claim 3, wherein the thickness of the insulating-material layer is less than the thickness of the first component and in which the method comprises:

- taking at least one second sheet,
- making in the second sheet at least one third recess for the first component, and

- attaching the second sheet to the insulating-material layer from the direction of the second surface.

6. (Cancelled)

7. (Withdrawn) A method according to Claim 5, wherein the insulating-material layer is of a first insulating material and the second sheet is of a second insulating material, which differs from the first insulating material.

8-10. (Cancelled).

11. (Previously Presented) A method according to Claim 3, wherein the first component attached to the first conductive layer is an unpacked microcircuit chip.

12. (Previously Presented) A method according Claim 3, wherein, in order to create a multi-layer circuit-board structure, additional insulating layers and conductive layers are manufactured on at least one of the first and the second surface.

13-15. (Cancelled)

16. (Currently Amended) An electronic module, comprising:

 a sheet, which has a first and a second surface, and which sheet includes an insulating-material layer between the first and the second surface,

 a first conductive pattern layer on the first surface of the sheet,

 at least one first recess in the sheet that extends through the second surface and the insulating-material layer as far as the first conductive pattern layer,

 a first component having a first contact surface with contact areas or contact protrusions, the first component placed in the first recess with the first contact surface of the first component facing the first surface,

 a first electrically insulating adhesive attaching the first component to the first conductive

pattern layer on the first surface of the sheet, and

first ~~connectors feed-throughs~~ connecting at least some of the contact areas or contact protrusions of the first component electrically to the first conductive pattern layer through first feed-throughs,

a second conductive pattern layer on the second surface of the sheet,

a second component, having a second contact surface with contact areas or contact protrusions and placed in the insulating-material layer with the second contact surface facing the second conductive pattern layer,

a second electrically insulating adhesive attaching the second component to the second conductive pattern layer, and

second ~~connectors feed-throughs~~ connecting at least some of the contact areas or contact protrusions of the second component electrically to the second conductive pattern layer through second feed-throughs.

17. (Currently Amended) The electronic module of Claim 16, wherein the first ~~connectors feed-throughs~~ are metal and form metallurgical bonds between at least some of the contact areas or contact protrusions of the first component and the first conductive pattern layer.

18. (Previously Presented) The electronic module of Claim 16, wherein at least one of the first and second component is an unpacked microcircuit chip.

19. (Previously Presented) The electronic module of Claim 16, comprising a further insulating layer and a further conductive layer on the first surface of the sheet.

20-21. (Cancelled)

22. (Currently Amended) A method according to Claim 3, wherein the at least some first electrical contacts feed-throughs are metal and metallurgically bond to at least some of the contact areas or contact protrusions of the first component and the first conductive pattern layer.

23. (Previously Presented) A method according to Claim 3, wherein the second electrically insulating adhesive is the same as the first electrically insulating adhesive.

24. (Previously Presented) A method according to Claim 3, wherein the attaching step further includes bringing the electrically insulating adhesive between the first component and the first conductive layer before inserting the first component in the first recess and allowing the electrically insulating adhesive to harden after inserting the first component in the first recess.

25. (Previously Presented) The electronic module of Claim 16, wherein the second electrically insulating adhesive is the same as the first electrically insulating adhesive.

26. (Previously Presented) The electronic module of Claim 16, wherein at least a portion of the electrically insulating adhesive is positioned between the first component and the first conductive layer.